ASEDCIATION CONNECTING ASEDCIATION CONNECTING International and Pan-American co	burn. Illinois. All rights reserved	under both lev	is docume rel parts, th	ent is a declaration ne declaration en	n of the substand compasses all lo	es within the manufactu wer level materials for w	rer listed item which the man	. Note: if th ufacturer ha	e item is an ass s engineering i	sembly with lower responsibility.	
IPC Web Site for Information on I http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information											
Company name*	name* Company unique ID			Unique ID Authority				Response Date*			
onsemi								2023-06-08			
Contact Name	Title - Contact		F	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance]	NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	Title - Representative		F	Phone - Representative*			Email - Representative*				
Product-Env-Stewards Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Iten	n Number Mfr Item Name	em Name		Effective Date	Version	Manufacturing Site		ight*	UOM	Unit Type	
FAN23S	SV04TMPX 4A 18V PoL Re	egulators		2023-06-08		PBB	83.	149	mg	Each	
Manufacturing Proccess Information						·					
Terminal Plating / Grid Array Material	Cerminal Base Alloy J-STD-020 M		ating	Peak Proces	s Body Tempera	ature Max Time at Peak	Temperature	Number	of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy 1		1		260	С	30	seconds	3			
Comments											
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds										
For more information regarding material composition	please refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.362	mg	Supplier	Silver (Ag)	7440-22-4		0.034	mg
			А	Lead (Pb)	7439-92-1	7a	1.2599	mg
			Supplier	Tin (Sn)	7440-31-5		0.0681	mg
Lead Frame	30.983	mg	Supplier	Silver (Ag)	7440-22-4		0.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.04	mg
			Supplier	Iron (Fe)	7439-89-6		0.744	mg
			Supplier	Copper (Cu)	7440-50-8		29.917	mg
Mold Compound-Black	46.6	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		4.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.466	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.008	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.932	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Vire Bond - Au	0.684	mg	Supplier	Gold (Au)	7440-57-5		0.684	mg
Wire Bond - Cu	0.6	mg	Supplier	Palladium (Pd)	7440-05-3		0.012	mg
			Supplier	Copper (Cu)	7440-50-8		0.588	mg